

Global Outsourced Semiconductor Assembly and Test Market (OSAT) Market with Focus on IC Packaging (2018-2022)

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Abstracts

Scope of the Report

The report titled “Global Outsourced Semiconductor Assembly and Test Market (OSAT) Market with Focus on IC Packaging: Size, Trends & Forecasts (2018-2022)”, provides an in-depth analysis of the global OSAT market by value and by region. Further, analysis includes IC Packaging market by value, by volume and by segment. The report also provides the analysis of the OSAT market by value for China region.

The report also assesses the key opportunities in the market and outlines the factors that are and will be driving the growth of the industry. Growth of the overall global OSAT market with focus on IC packaging market has also been forecasted for the period 2018-2022, taking into consideration the previous growth patterns, the growth drivers and the current and future trends.

The OSAT market with focus on IC packaging market is dominated by few players, but there are other new players, private label players as well. However, the competition in the global OSAT market with focus on IC packaging market is dominated by Advanced Semiconductor Engineering, (ASE) Inc., Amkor Technology, Inc., ChipMOS Technologies Inc. (ChipMOS), Mubadala Investment Company (GlobalFoundries Inc.), who are also profiled with their financial information and respective business strategies.

Country Coverage

China

Company Coverage

Advanced Semiconductor Engineering, (ASE) Inc.

Amkor Technology, Inc.

ChipMOS Technologies Inc. (ChipMOS)

Mubadala Investment Company (GlobalFoundries Inc.)

Executive Summary

An Integrated Circuit (IC) is defined as the circuit that is comprised of inseparable and electrically interconnected elements. An IC is basically a semiconductor wafer in which millions of components, like, tiny resistors, capacitors, and transistors, are fabricated. ICs have distinct characteristics like, they are very small in size, have less weight, require low power, and are highly reliable, etc.

The OSATs offer Integrated Circuit packaging services on the open market to the integrated semiconductor manufacturers (ISMs), and fabless companies, and to IDMs and foundries as well. Outsourced Semiconductor Assembly and Test (OSAT) provide third-party Integrated Circuit (IC) packaging and test services.

The OSAT market can be segmented on the basis of technology used in IC packaging. OSAT is based on three major IC packaging technologies, named as Wirebond Packaging, Flip Chip Packaging and Wafer level Packaging.

The global OSAT market with focus on IC packaging has increased at a significant CAGR over the years and projections are made that the market would rise in the next four years i.e. 2018-2022 tremendously. The OSAT market is expected to increase due to rising automotive production, rising Internet of Things (IoT), growing personal electronics, increasing smartphone users, rising urban population etc. Yet the market faces some challenges such as volatile demand from cryptocurrency, etc.

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